VAOL-S4GT4

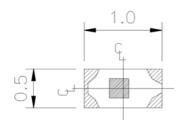
Features

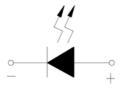
- Fit automatic placement equipment.
- Fit Compatible with infrared and vapor phase reflow solder process.
- Pb-free.
- RoHS compliant.

Descriptions

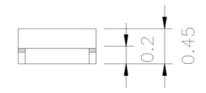
- For higher packing density.
- For minature applications.
- Water clear lens .
- Chip material : AlGaInP.
- Emitting color: Yellow Green.

Package Outline Dimensions

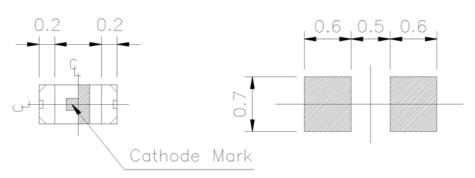




POLARITY



For Reflow Soldering



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm







Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit			
Reverse Voltage	V_R	5	V			
Forward Current	${ m I}_{ m F}$	25	mA			
Operating Temperature	Topr	-40 ~ +85	°C			
Storage Temperature	Tstg	-40 ~ +90	$^{\circ}$ C			
Soldering Temperature	Tsol	260 (for 5 second)	°C			
Electrostatic Discharge (HBM)	ESD	2000	V			
Power Dissipation	Pd	60	mW			
Peak Forward Current	т	(0)	mA			
(Duty 1/10 @1KHz)	Ifp	60				
		Reflow Soldering: 260 °C f				
Soldering Temperature	Tsol	Hand Soldering: 350 °C for 3 sec.				

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	*Chip Rank	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	Iv	E1	10	15		mcd	
		E2	20	25			
		ЕЗ	30	35			
		E4	40	45			
Viewing Angle θ	2 1/2			120		deg	I _F =20mA
Peak Wavelength	λр			575		nm	IF=20mA
Dominant Wavelength	λd			573		nm	
Spectrum Radiation Bandwidth	Δλ			20		nm	
Forward Voltage	VF		1.7	2.0	2.4	V	
Reverse Current	Ir				10	μ A	V _R =5V

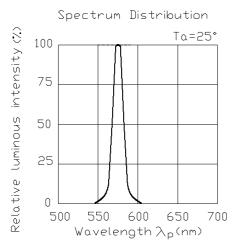
Specific binning requirements- please contact our home office

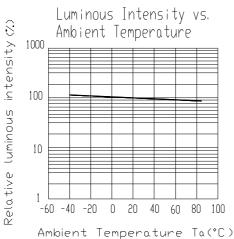


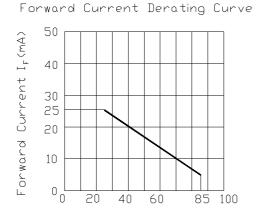




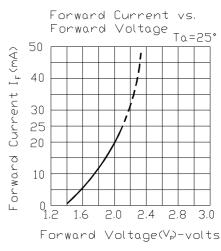
Typical Electro-Optical Characteristics Curves

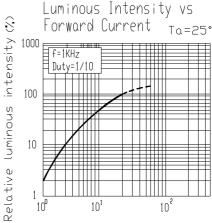


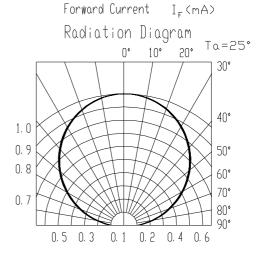




Ambient Temperature Ta(°C)



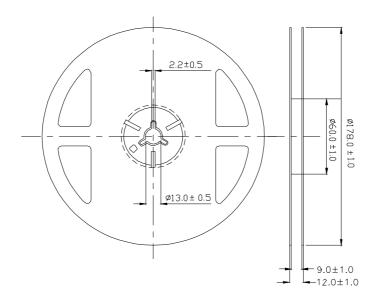








Reel Dimensions

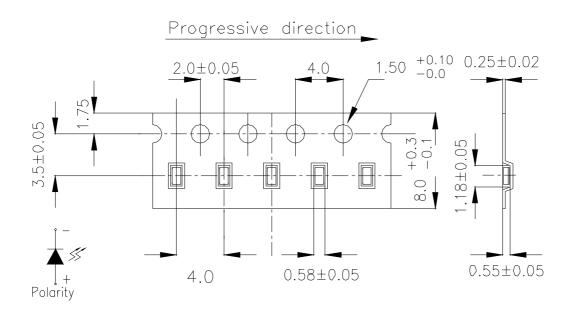


Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm



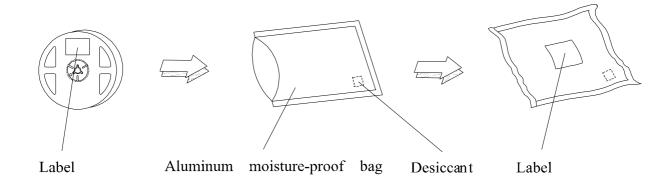


Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

Moisture Resistant Packaging

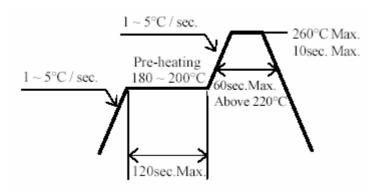






Soldering Condition

1.Pb-free solder temperature profile



- 2.Reflow soldering should not be done more than two times.
- 3 When soldering, do not put stress on the LEDs during heating.
- 4 After soldering, do not warp the circuit board.

Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.





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